## **Panasonic**

# MA3X704D (MA704WA), MA3X704E (MA704WK)

### Silicon epitaxial planar type

For switching

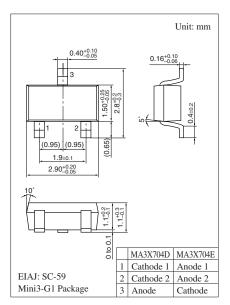
For wave detection

#### ■ Features

- Two MA3X704A (MA704A) is contained in one package
- $\bullet$  Low forward voltage  $V_F$  and good wave detection efficiency  $\eta$
- Small temperature coefficient of forward characteristic
- Small reverse current I<sub>R</sub>

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

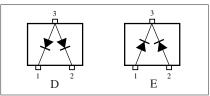
Parameter		Symbol	Rating	Unit
Reverse voltage		$V_R$	30	V
Maximum peak reverse voltage		$V_{RM}$	30	V
Peak forward current	Single	$I_{FM}$	150	mA
	Double		110	
Forward current	Single	$I_{F}$	30	mA
	Double		20	
Junction temperature		T <sub>j</sub>	125	°C
Storage temperature		$T_{stg}$	-55 to +125	°C



#### Marking Symbol

• MA3X704D: M2P • MA3X704E: M2R

#### Internal Connection

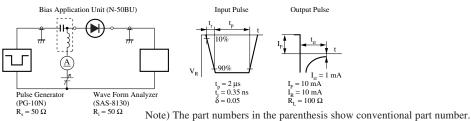


#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

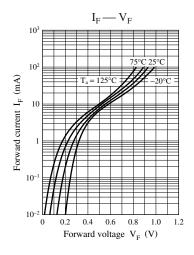
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 1 \text{ mA}$			0.4	V
	V <sub>F2</sub>	$I_F = 30 \text{ mA}$			1.0	
Reverse current	$I_R$	$V_R = 30 \text{ V}$			1	μΑ
Terminal capacitance	$C_{t}$	$V_R = 1 \text{ V, } f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 10 \text{ mA}$		1.0		ns
		$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}$ , $f = 30 MHz$		65		%
		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

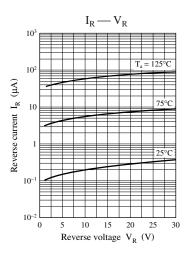
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

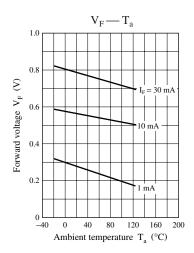
- This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 2 GHz.
- 4. \*: t<sub>rr</sub> measurement circuit

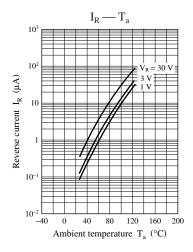


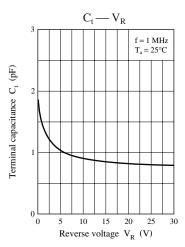
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